

ALCOR - dRICH Readout

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INFN Torino

ePIC Electronics & DAQ WG meeting
eRD109 Monthly Progress Reports

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Summary of ALCOR activities

ALCORv3

- **ALCOR-64 MPW** tape-out on April 8th
 - Wafers **dicing** this week, preparing shipment
 - **50 singulated dies** expected for end of August, then **packaging**
 - First test results by the end of this year
- **November beam test** (CERN SPS) will use old **ALCORv2** boards (coupled with new **RDO FPGA** readout using dedicated FEB adapter card), now preparing new ALCORv2 FE-DUAL boards and spares

FEB

- **Final FEB**: design completed on May
- 1st version includes 2 **SMA SiPM outputs** to inspect SiPM signals on scope → study **SiPM annealing** (and power dissipation) using final FEB, initially also without ALCOR v3
- Expected to be delivered very soon

